DESCRIPTION

The 82S136 and 82S137 are field programmable, which means that custom patterns are immediately available by following the fusing procedure given in this data sheet. The standard 82S136 and 82S137 are supplied with all outputs at logical low. Outputs are programmed to a logic high level at any specified address by fusing a Ni-Cr link matrix.

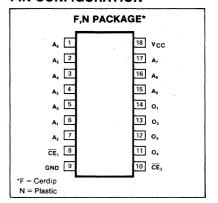
These devices include on-chip decoding and 2 chip enable inputs for ease of memory expansion. They feature either open collector or tri-state outputs for optimization of word expansion in bused organizations.

Both 82S136 and 82S137 devices are available in the commercial and military temperature ranges. For the commercial temperature range (0°C to +75°C) specify N82S136/137, F or N, and for the military temperature range (-55°C to +125°C) specify S82S136/137, F.

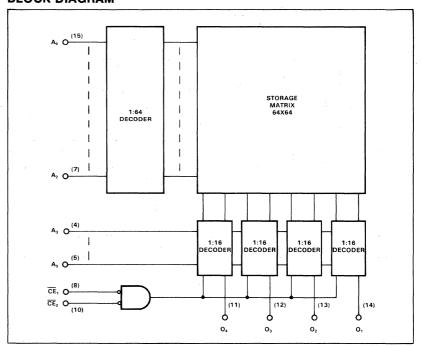
FEATURES

- Address access time: N82S136/137: 60ns max S82S136/137: 80ns max
- Power dissipation: .13mW/bit typ
- Input loading: N82S136/137: -100µA max S82S136/137: -150µA max
- On-chip address decoding
- Output options:
 82S136: Open collector
 82S137: Tri-state
- No separate fusing pins
- Unprogrammed outputs are low level
- Fully TTL compatible

PIN CONFIGURATION



BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

	PARAMETER	RATING	UNIT
Vcc	Supply voltage	+7	Vdc
Vin	Input voltage	+5.5	Vdc
	Output voltage		Vdc
Voн	High (82S136)	+5.5	
Vo	Off-state (82S137)	+5.5	
	Temperature range		°C
TA	Operating		
	N82S136/137	0 to +75	
	S82S136/137	-55 to +125	
T _{STG}	Storage	-65 to +150	

$\begin{array}{ll} \textbf{DC ELECTRICAL CHARACTERISTICS} & N82S136/137: \ 0^{\circ}\text{C} \leq T_{A} \leq +75^{\circ}\text{C}, \ 4.75\text{V} \leq V_{CC} \leq 5.25\text{V} \\ & S82S136/137: \ -55^{\circ}\text{C} \leq T_{A} \leq +125^{\circ}\text{C}, \ 4.5\text{V} \leq V_{CC} \leq 5.5\text{V} \\ \end{array}$

	PARAMETER	TEST CONDITIONS ¹	N82S136/137			S82S136/137			LINUT
FARAMETER		TEST CONDITIONS	Min	Min Typ ² Max		Min Typ ² Max		Max	UNIT
V _{IL} V _{IH}	Input voltage Low High		2.0		.85	2.0		.80	V
V _{IC}	Clamp	I _{IN} = -18mA		-0.8	-1.2		-0.8	-1.2	
V _{OL} V _{OH}	Output voltage Low High (82S137)	I _{OUT} = 16mA CE = Low, I _{OUT} = -2mA, High stored	2.4		0.45	2.4		0.5	V
hu ha	Input current Low High	V _{IN} = 0.45V V _{IN} = 5.5V			-100 40			-150 50	μА
lolk lo(off) los	Output current Leakage (82S136) Off-state (82S137) Short circuit (82S137)	$\overline{\underline{CE}} = \text{High, V}_{\text{OUT}} = 5.5\text{V}$ $\overline{\underline{CE}} = \text{High, V}_{\text{OUT}} = 0.5\text{V}$ $\overline{\underline{CE}} = \text{High, V}_{\text{OUT}} = 5.5\text{V}$ $\overline{\underline{V}_{\text{OUT}}} = 0\text{V}$	-20		40 -40 40 -70	-15		60 -60 60 -85	μA μA mA
lcc	V _{CC} supply current	4.4		105	140		105	140	mA
Cin Cout	Capacitance Input Output	$V_{CC} = 5.0V$ $V_{IN} = 2.0V$ $V_{OUT} = 2.0V$		5 8			5 8		pF

AC ELECTRICAL CHARACTERISTICS $R_1 = 270\Omega, R_2 = 600\Omega, C_L = 30pF^1$

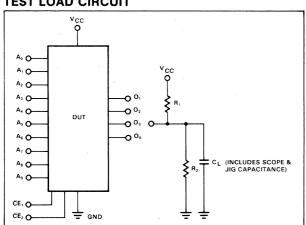
$$\begin{split} &N82S136/137\colon\ 0^{\circ}C \leq T_{A} \leq +75^{\circ}C,\ 4.75V \leq V_{CC} \leq 5.25V \\ &S82S136/137\colon\ -55^{\circ}C \leq T_{A} \leq +125^{\circ}C,\ 4.5V \leq V_{CC} \leq 5.5V \end{split}$$

	то	FROM	N82S136/137			S82S136/137			
PARAMETER			Min	Typ ²	Max	Min	Typ ²	Max	UNIT
Access time									ns
TAA	Output	Address		40	60		40	80	l
T _{CE}	Output	Chip enable		20	30		20	40	
Disable time									ns
T _{CD}	Output	Chip disable		20	30		20	40	

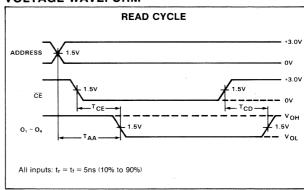
NOTES

- 1. Positive current is defined as into the terminal referenced.
- 2. All typical values are at $V_{CC} = 5V$, $T_A = 25^{\circ}C$.

TEST LOAD CIRCUIT



VOLTAGE WAVEFORM



PROGRAMMING SYSTEMS SPECIFICATIONS (Testing of these limits may cause programming of device.) TA = +25°C

				LIMITS		
*.	PARAMETER	TEST CONDITIONS	Min	Min Typ		UNIT
VCCP	Power supply voltage To program ¹	$I_{CCP}=375\pm75$ mA, Transient or steady state	8.5	8.75	9.0	: V
Vcch Vccl	Verify limit Upper Lower		5.3 4.3	5.5 4.5	5.7 4.7	V
Vs ICCP	Verify threshold ² Programming supply current	V _{CCP} = +8.75 ± .25V	1.4 300	1.5	1.6 450	V mA
VIH VIL	Input voltage High Low		2.4 0	0.4	5.5 0.8	V
lin lic	Input current High Low	$V_{IH} = +5.5V$ $V_{IL} = +0.4V$			50 -500	μΑ
Vоит	Output programming voltage ³	$I_{OUT} = 200 \pm 20$ mA, Transient or steady state	16.0	17.0	18.0	V
lout	Output programming current	$V_{OUT} = +17 \pm 1V$	180	200	220	mA
T _R	Output pulse rise time		10		50	μs
tp	CE programming pulse width	•	0.3	0.4	0.5	ms
t_{D}	Pulse sequence delay	· · · · · · · · · · · · · · · · · · ·	10			μs
TPR	Programming time	V _{CC} = V _{CCP}	1	ľ	12	sec
TPSI	Initial programming pause	$V_{CC} = 0V$	6			sec
T _{PR} T _{PR} +T _{PS}	Programming duty cycle ⁴				50	~%
FL	Fusing attempts per link				2	cycle

NOTES

- 1. Bypass V_{CC} to GND with a $0.01\mu F$ capacitor to reduce voltage spikes. 2. V_S is the sensing threshold of the PROM output voltage for a programmed bit. It normally constitutes
- the reference voltage applied to a comparator circuit to verify a successful fusing attempt. 3. Care should be taken to insure the 17 \pm 1V output voltage is maintained during the entire fusing cycle. The recommended supply is a constant current source clamped at the specified voltage limit.
- 4. Programming duty cycle is 50% after continuous programming at 100% duty cycle.
- This is an updated method of programming and does not obsolete any programming systems presently being used.

PROGRAMMING PROCEDURE

- 1. Terminate all device outputs with a $10K\Omega$ resistor to V_{CC} . Apply $\overline{CE}_1 = \text{High } \overline{CE}_2 =$
- 2. Select the Address to be programmed, and raise V_{CCP} to $V_{CCP} = 8.75 \pm .25V$.
- 3. After $10\mu s$ delay, apply $V_{OUT} = +17 \pm 1V$ to the output to be programmed. Program one output at the time.
- 4. After 10μs delay, pulse the CE₁ input to logic low for 0.3 to 0.5ms.
- 5. After $10\mu s$ delay, remove +17V from the programmed output.
- 6. To verify programming, after $10\mu s$ delay, lower V_{CC} V_{CCH} = $+5.5 \pm .2$ V, and apply a logic low level to the CE input. The programmed output should remain in the high state. Again, lower V_{CC} to V_{CCL} =
- $+4.5 \pm .2V$, and verify that the programmed output remains in the high state.
- 7. Raise V_{CC} to V_{CCP} = 8.75 \pm .25V, and repeat steps 3 through 6 to program other bits at the same address.
- 8. After 10 µs delay, repeat steps 2 through 7 to program all other address locations.

TYPICAL PROGRAMMING SEQUENCE

